Overview

## HP ProOne 240 23.8 inch G10 All-in-One Desktop PC



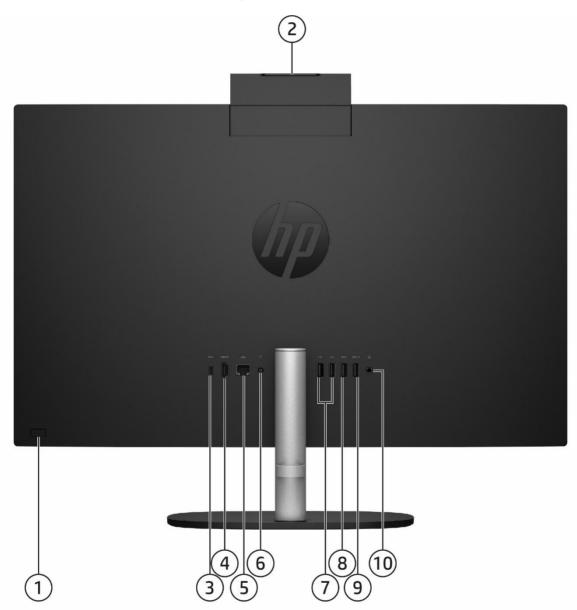
Front

- 1. Pull-up tiltable 5MP webcam and microphone
- 2. Speakers (downfiring)



Overview

## HP ProOne 240 23.8 inch G10 All-in-One Desktop PC



Rear

- 1. Power button
- 2. Pull-up webcam
- 3. One (1) Type-C USB 5Gbps signaling rate port
- 4. HDMI 1.4 out connector
- 5. RJ-45 (network) jack
- 6. Power connector

- 7. Two (2) Type-A Hi-Speed USB 480Mbps signaling rate ports
- 8. One (1) Type-A SuperSpeed USB 5Gbps signaling rate port
- 9. One (1) Type-A SuperSpeed USB 5Gbps signaling rate port with HP Sleep and Charge
- 10. Microphone/Headphone Combo Jack



Overview

### AT A GLANCE

- Choice of Windows 11 Pro, Windows 11 Home, and FreeDOS.
- Integrated All-in-One form factor.
- 23.8-inch diagonal widescreen Full HD anti-glare display.
- Latest Intel<sup>®</sup> Core<sup>™</sup> Ultra Processors with Intel<sup>®</sup> Graphics.
- Up to 32GB of DDR5 5600 SODIMM.
- Integrated 10/100/1000 Gigabit LAN Ethernet Controller.
- Wi-Fi 6 wireless connectivity.
- Integrated HD audio card and stereo speakers.
- Integrated 5MP (Pixel size: 1.12µm x 1.12µm) pull-up tiltable camera to ensure no accidental recording to safeguard user's privacy.
- Storage options with up to 1TB SSD and 1TB HDD, including optional 2<sup>nd</sup> HDD.
- Optional HP external USB DVD/RM Drive.
- TPM 2.0 support.
- Low halogen materials, ENERGY STAR<sup>®</sup> certified and EPEAT<sup>®</sup> gold registered where applicable.
- Optional HP Care Pack available. Terms and conditions vary by country. Certain restrictions and exclusions apply.

**NOTE:** See important legal disclosures for all listed specs in their respective features sections.



Features

### **OPERATING SYSTEMS**

Preinstalled	Windows 11 Pro <sup>1</sup>
	Windows 11 Home - HP recommends Windows 11 Pro for Business <sup>1</sup>
	Windows 11 Home Single Language - HP recommends Windows 11 Pro for Business <sup>1</sup>
	FreeDOS
Pre-installed (other)	FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

#### **PROCESSORS\***

#### Intel<sup>®</sup> Core<sup>™</sup> Ultra 7 processor 155U<sup>1,2</sup>

Up to 3.8 GHz E-core 4.8 P-core Max Turbo frequency 12 MB Intel<sup>®</sup> Smart Cache, 12 cores, 14 threads Integrated Intel<sup>®</sup> Graphics Supports DDR5 memory up to 5600MT/s data rate<sup>3</sup>

#### Intel<sup>®</sup> Core<sup>™</sup> Ultra 5 processor 125U<sup>1,2</sup>

Up to 3.6 GHz E-core 4.3 P-core Max Turbo frequency 12 MB Intel® Smart Cache, 12 cores, 14 threads Integrated Intel® Graphics Supports DDR5 memory up to 5600MT/s data rate<sup>3</sup>

#### Intel<sup>®</sup> Core<sup>™</sup> i7-1355U<sup>1</sup>

Up to 3.7 GHz E-core 5.0 P-core Max Turbo frequency 15 MB L3 cache, 10 cores, 12 threads Integrated Intel<sup>®</sup> Iris<sup>®</sup> X<sup>e</sup> Graphics Supports DDR4 memory up to 3200MT/s data rate<sup>3</sup>

#### Intel<sup>®</sup> Core<sup>™</sup> i5-1335U<sup>1</sup>

Up to 3.4 GHz E-core 4.6 P-core Max Turbo frequency 12 MB L3 cache, 10 cores, 12 threads Integrated Intel<sup>®</sup> Iris<sup>®</sup> X<sup>®</sup> Graphics Supports DDR4 memory up to 3200MT/s data rate<sup>3</sup>

#### Intel<sup>®</sup> Core<sup>™</sup> i5-1334U<sup>1</sup>

Up to 3.4 GHz E-core 4.6 P-core Max Turbo frequency 12 MB L3 cache, 10 cores, 12 threads Integrated Intel<sup>®</sup> Iris<sup>®</sup> X<sup>e</sup> Graphics Supports DDR4 memory up to 3200MT/s data rate<sup>3</sup>

#### Intel<sup>®</sup> Core<sup>™</sup> i3-N300<sup>1</sup>

Up to 3.8 GHz Max Turbo frequency 6 MB L3 cache, 8 cores, 8 threads Integrated Intel<sup>®</sup> UHD Graphics Supports DDR4 memory up to 3200MT/s data rate<sup>3</sup>



Features

#### Intel<sup>®</sup> Processor N200

Up to 3.7 GHz burst frequency 6 MB cache, 4 cores, 4 threads Integrated Intel<sup>®</sup> UHD Graphics Supports DDR4 memory up to 3200 MT/s data rate<sup>3</sup>

1. Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

 Features and software that require a NPU may require software purchase, subscription or enablement by a software or platform provider, and third party software may have specific configuration or compatibility requirements. Performance varies by use, configuration, and other factors.
 Actual data rate is determined by both the system's configured processor and memory module installed.

**NOTE**: In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

#### GRAPHICS

## Integrated

Intel<sup>®</sup> Iris<sup>®</sup> X<sup>e</sup> Graphics<sup>1</sup> Intel<sup>®</sup> Graphics Intel<sup>®</sup> UHD Graphics

1: Intel<sup>®</sup> Iris<sup>®</sup> Xe Graphics capabilities require system to be configured with Intel<sup>®</sup> Core<sup>™</sup> i5 or i7 processors and dual channel memory. Intel<sup>®</sup> Iris<sup>®</sup> Xe Graphics with Intel<sup>®</sup> Core<sup>™</sup> i5 or 7 processors and single channel memory will only function as UHD graphics.

#### DISPLAY

Non-Touch 23.8" diagonal FHD IPS anti-glare WLED-backlit (1920 x 1080)

## **STORAGE AND DRIVES\***

**NOTE:** Starting from November 1<sup>st</sup>, 2023, all shipments will require Windows to be installed when selecting a SSD. HDD can only be configured as additional data drives and not as the boot drive.

#### M.2 PCIe NMVe Solid State Drives (SSD)

256GB 2280 PCIe NVMe Solid State Drive 512GB 2280 PCIe NVMe Solid State Drive 1TB 2280 PCIe NVMe Solid State Drive 512GB 2280 PCIe NVMe TLC Solid State Drive 1TB 2280 PCIe NVMe TLC Solid State Drive

2.5-inch SATA Hard Disk Drives (HDD) 1TB 7200RPM 2.5 in HDD

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB is reserved (for Windows) for system recovery software.



Features

### MEMORY

Maximum DDR5 SODIMM up to 5600MT/s

**Memory Slots** 

2 SODIMM<sup>1</sup>

#### **Available Configurations**

4GB (4GB x1) 8GB (4GB x2)<sup>1,2</sup> 8GB (8GB x1) 16GB (8GB x2)<sup>1,2</sup> 16GB (16GB x1) 32GB (16GB x2)<sup>1,2</sup>

Dual Channel memory not supported with Intel N200 or Intel<sup>®</sup> Core<sup>™</sup> i3-N300 processors.
 Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.
 NOTE: Actual data rate is determined by both the system's configured processor and memory module installed.

### **NETWORKING/COMMUNICATIONS**

#### Wireless LAN

 $\label{eq:selection} \begin{array}{l} \mbox{Realtek}^{\circledast} \ 8852 \mbox{BE Wi-Fi} \ 6^1 \ (802.11 \mbox{ax}) \ 2x2 \ Wi-Fi^{\circledcirc} \ M.2 \ Card^2 \\ \mbox{Realtek}^{\circledcirc} \ 8852 \mbox{BE-VS Wi-Fi} \ 6^1 \ (802.11 \mbox{ax}) \ 1x1 \ Wi-Fi^{\circledcirc} \ M.2 \ Card^2 \\ \mbox{Realtek}^{\circledcirc} \ 8852 \mbox{BE-VT Wi-Fi} \ 6^1 \ + \mbox{Bluetooth}^{\circledast} \ 5.4 \ WW \ WLAN^2 \end{array}$ 

#### Ethernet (RJ-45) Integrated

Realtek® RTL8111HSH-CG Gigabit Ethernet Controller

1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11 ax) is backwards compatible with prior 802.11 specs.

2. Must be configured at time of purchase.

## AUDIO/MULTIMEDIA

#### **High Definition Audio**

Integrated Realtek ALC3274 Audio Codec High performance integrated stereo speakers 3.5mm combo (microphone/headphone) jack

#### Webcams & Mic

Integrated tiltable 5MP webcam (Pixel size: 1.12µm x 1.12µm), Up to 30 frames/sec, dual array microphone included



### Features

### **KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS**

#### Keyboards

HP Universal USB Wired Keyboard

#### Mice

HP USB Hardened Optical Mouse HP USB Universal Mouse

#### Keyboard and Mouse Combo

HP Universal wireless Keyboard & Mouse combo

NOTE: Availability may vary by country

### SOFTWARE AND SECURITY

#### **HP Support**

HP PC Hardware Diagnostics HP Cloud Recovery HP Support Assistant

#### Internet Security and Antivirus

McAfee LiveSafe (30-day subscription)<sup>1</sup>

## Product Setup

myHP

**Security Features** Trusted Platform Module (TPM) 2.0 (firmware)<sup>2,3</sup>

#### **Productivity** Xerox<sup>®</sup> DocuShare<sup>®</sup> (90 days free trial offer)<sup>4</sup> Microsoft 365 (sold separately and requires Internet access for activation)

1. 30 days trial period. Internet access required to receive updates. First update included. Subscription required for updates thereafter

2. TPM feature will not be supported on machines pre-configured with FreeDOS and Linux

3. In selected countries, machines pre-configured with Windows OS will be shipped with TPM disabled.

4. Simply sign up and start using Xerox<sup>®</sup> DocuShare<sup>®</sup> Go. No credit card. No obligation. Data will become unavailable unless a subscription is entered before the end of the 90 days free trial period. See visit https://xerox.com/docusharego for details.

#### POWER

#### **Power Supply**

HP Smart 65W External AC power adapter HP Smart 90W External AC power adapter



Features

## **PORTS/SLOTS**

#### Rear I/O Ports

One (1) Type-C SuperSpeed USB 5Gbps signaling rate ports One (1) Type-A SuperSpeed USB 5Gbps signaling rate ports One (1) Type-A SuperSpeed USB 5 Gbps port with HP Sleep and Charge Two (2) Type-A Hi-Speed USB 480Mbps signaling rate ports One (1) RJ-45 (network) jack One (1) HDMI 1.4 out connector One (1) Microphone/Headphone Combo Jack One (1) DC in power

#### Internal I/O Ports

One (1) M.2 PCIe x1 2230 (for WLAN) One (1) M.2 PCIe x4 2280 (for storage) One (1) SATA storage connector

#### Bays

One (1) 2.5" internal storage drive

### **WEIGHTS & DIMENSIONS**

#### Weight

23.8 Non-Touch Product Weight (Unboxed)

	<b>Basic Stand</b> 5.37 kg, 11.84 lbs
23.8 Shipping Weight (Boxed)	8.80 kg, 19.40 lbs
23.8 Shipping Weight (Pallet)	225.2 kg, 496.5 lbs

#### Dimension

23.8 System Dimensions

Without Stand	540.62 x 183.7 x 351.43 mm 21.28 x 7.23 x 13.84 in
Basic Stand	540.62 x 183.7 x 419.01 mm 21.28 x 7.23 x 16.50 in
23.8 Shipping Dimensions (Boxed)	641 x 277 x 525 mm 25.2 x 10.7 x 20.6 in
23.8 Shipping Dimensions (Pallet)	1200 x 1000 x 2235 mm 47.24 x 39.37 x 88 in
23.8 Pallet Quantity (Sea/ Rail)	24
23.8 Pallet Quantity (Air)	12



### Features

## **UNIT ENVIRONMENT AND OPERATING CONDITIONS<sup>9</sup>**

• Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.

• Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.

• Never restrict airflow into the computer by blocking any vents or air intakes.

• Do not stack computers on top of each other or place computers so near each other that they are subject to each other's recirculated or preheated air.

• Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.

• If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

• Low halogen (chassis, all internal components and modules)<sup>1</sup>

Temperature Range	Operating: 50° to 95° F (10° to 35° C)* Non-operating: -22° to 140° F(-30° to 60° C)
Relative Humidity	Operating: 10% to 90% (non-condensing at ambient) Non-operating: 5% to 95% (non-condensing at ambient)
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50000ft (15240 m)

1. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

**NOTE:** Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

## **ENVIRONMENTAL & INDUSTRY**

#### Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

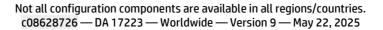
- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEAT<sup>®</sup> Gold registered in the United States. See <a href="http://www.epeat.net">http://www.epeat.net</a> for registration status in your country.
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label\*

#### Sustainable Impact Specifications

- Product Carbon Footprint (hp.com)
- Ocean-bound plastic in CPU fan, stand
- 25% post-consumer recycled plastic
- 10% recycled metal
- Low halogen<sup>1</sup>
- Outside Box and corrugated cushions are 100% sustainably sourced and recyclable
- Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".





## Features

Energy Consumption (in accordance with US ENERGY STAR®	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
<b>test method)</b> Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off	17.78 W 5.75 W 1.58 W 0.34 W	17.86 W 5.83 W 1.61 W 0.35 W	17.62 W 5.60 W 1.54 W 0.32 W	
	<b>NOTE:</b> Energy efficiency data liste the model family. HP computers r applicable U.S. Environmental Pro computers. If a model family does energy efficiency data listed is for efficiency power supply, and a Min generator on HP's 3rd party option http://www.hp.com/go/option	ed is for an ENERGY STAR® c narked with the ENERGY ST otection Agency (EPA) ENER of a toffer ENERGY STAR® c r a typically configured PC fe crosoft Windows® operating n store for solar generator a	ertified product if offered within AR® Logo are certified with the GY STAR® specifications for ertified configurations, then eaturing a hard disk drive, a high g system. Search keyword	
<b>Heat Dissipation*</b> Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off	<b>115VAC, 60Hz</b> 61 BTU/hr 20 BTU/hr 5 BTU/hr 1 BTU/hr	<b>230VAC, 50Hz</b> 61 BTU/hr 20 BTU/hr 6 BTU/hr 1 BTU/hr	<b>100VAC, 50Hz</b> 60 BTU/hr 19 BTU/hr 5 BTU/hr 1 BTU/hr	
	<b>NOTE:</b> Heat dissipation is calculat is attained for one hour.	ed based on the measured v	watts, assuming the service level	
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L <sub>WAd</sub> , bels)		Sound Pressure (L <sub>PAm</sub> , decibels)	
Typically Configured – Idle Fixed Disk – Random writes Longevity and Upgrading	1.918.72.321.9This product can be upgraded, possibly extending its useful life by several years.Upgradeable features and/or components contained in the product may include:			
	Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.			
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC			
	Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight			
	Battery size: CR2032 (coin cell) Battery type: Lithium			
Additional Information	<ul> <li>(RoHS) directive - 201</li> <li>This HP product is des Electronic Equipment</li> <li>This product is in com California; Safe Drink</li> <li>This product is in com Gold level, see http://</li> <li>Plastics parts weighin ISO11469 and ISO104</li> </ul>	1/65/EC. signed to comply with the (WEEE) Directive – 2002, upliance with California Pri ing Water and Toxic Enfo upliance with the IEEE 168 www.epeat.net ng over 25 grams used in 13.	/96/EC. roposition 65 (State of	



## Features

Packaging Materials	External:	PAPER/Corrugated	1218 g
		PAPER/ Paperboard	335 g
		PAPER/Molded Pulp	1218 g
	Internal:	PLASTIC/Other	982 g
		OTHER/Other	36 g
	The plastic pa	ackaging material contains at lea	ast 90% recycled content.
RoHS Compliance	The corrugated paper packaging materials contains at least 90% recycle		ns. We were among the first companies on (EU) Restriction of Hazardous vorldwide through the HP GSE. HP has
	industry-wide of additional s	elimination of substances of con	play an important role in promoting ncern. We have supported the inclusion s, and certain phthalates—in future l electronics products.
	RoHS requiren continue to ex		Idwide compliance with the new EU oducts by July 2013, and we will ent to include further restricted
	To obtain a co statement.	py of the HP RoHS Compliance S	tatement, see HP RoHS position
Material Usage	limits (refer to http://www.h Asbes Certa Certa Certa Cadm Chlor Chlor Form Halog Lead Lead Lead Merco Nicke frequ Ozon Polyb Polyb Polyb Polyb Polyb Polyb Polyb Rolyb Polyb Polyb Rolyb Polyb Rolyb	the HP General Specification for b.com/hpinfo/globalcitizenship/ stos in Azo Colorants in Brominated Flame Retardants dants in plastics ium inated Hydrocarbons inated Paraffins aldehyde genated Diphenyl Methanes carbonates and sulfates and Lead compounds uric Oxide Batteries l – finishes must not be used on ently handled or carried by the u e Depleting Substances forominated Biphenyl Ethers (PBB hlorinated Biphenyl Cyides (PBB hlorinated Biphenyl (PCB) hlorinated Terphenyls (PCT) inyl Chloride (PVC) – except for v aging has been voluntarily remove	environment/pdf/gse.pdf): 5 – may not be used as flame the external surface designed to be user. SES) BOS) wires and cables, and certain retail ved from most applications.
		nents are available in all regions/co – Worldwide — Version 9 — May 22	

Features	
	• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage End-of-life Management and Recycling	<ul> <li>HP follows these guidelines to decrease the environmental impact of product packaging: <ul> <li>Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.</li> <li>Eliminate the use of ozone-depleting substances (ODS) in packaging materials.</li> <li>Design packaging materials for ease of disassembly.</li> <li>Maximize the use of post-consumer recycled content materials in packaging materials.</li> <li>Use readily recyclable packaging materials such as paper and corrugated materials.</li> <li>Reduce size and weight of packages to improve transportation fuel efficiency.</li> <li>Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.</li> </ul> </li> <li>HP Inc. offers end-of-life HP product return and recycling programs in many</li> </ul>
	<ul> <li>geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office.</li> <li>Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</li> <li>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and resell HP equipment.</li> </ul>
HP, Inc. Corporate Environmental Information	For more information about HP's commitment to the environment: Global Citizenship Report https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06040843
	Eco-label certifications HP Sustainable Impact & Documents & Reports   HP® Official Site ISO 14001 certifications: https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c04777932
Footnotes	1. External power supplies, power cords, cables and peripherals are not Low Halogen. Service



parts obtained after purchase may not be Low Halogen.

Technical Specifications – Display

## **ALL-IN-ONE DISPLAY PANEL SPECIFICATIONS**

#### 23.8" diagonal FHD IPS anti-glare WLED-backlit (1920 x 1080)

Non-touch

IPS WLED Backlit LCD
527.04 x 296.46
1920 x 1080
60 Hz @ 1920 x 1080
16:9
0.2745 x 0.2745
1000:1
250nits
178 ° x 178 °
30,000 hours minimum
Up to 16.7 million colors with the use of FRC technology
NTSC 72%
Yes
14ms
Warm (6500K)

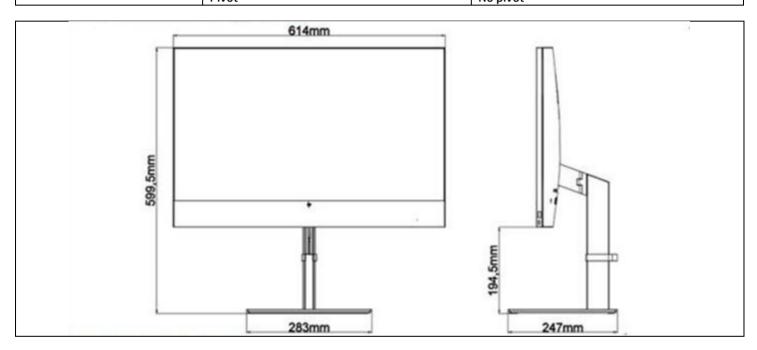
**NOTE**: All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



Technical Specifications – Stand

## **ALL-IN-ONE STAND SPECIFICATIONS**

Standard stand:	Tilt angle	-5° to +20°
	Rotation (Swivel)	None
Adjustable Height Stand:	Height - Vertical/Landscape Adjustment	130mm (±2 mm)
	Portrait Adjustment	No portrait
	Tilt Angle	-5° to +18° (±2°) in landscape and portrait
	Rotation (Swivel)	86° (±4°) (45 left, 45 right)
	Pivot	No pivot





Technical Specifications – Storage

### **STORAGE AND DRIVES**

**NOTE:** Starting from November 1<sup>st</sup>, 2023, all shipments will require Windows to be installed when selecting a SSD. HDD can only be configured as additional data drives and not as the boot drive.

1TB 7200RPM 2.5in SATA HDD			
Capacity	1TB		
Rotational Speed	7,200 rpm		
Interface	SATA 6 Gb/s		
Buffer Size	64 MB		
Logical Blocks	1,953,525,168		
Seek Time	11 ms (Average)		
Height	1 in/2.54 cm		
Width (nominal)	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm		
Operating Temperature	41° to 131°F (5° to 55°C)		

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

#### 128GB M.2 2230 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	128GB
Height	2.3mm
Length	30mm
Width	22mm
Interface	PCIE NVMe
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 780MB/s
Logical Blocks	290,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	Pyrite

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe SSD			
Drive Weight	< 10g		
Capacity	256GB		
Height	2.38mm		
Length	80mm		
Width	22mm		
Interface	PCIE Gen4		
Maximum Sequential Read	Up to 1600MB/s		
Maximum Sequential Write	Up to 780MB/s		
Logical Blocks	500,118,192		



Not all configuration components are available in all regions/countries. c08628726 — DA 17223 — Worldwide — Version 9 — May 22, 2025

Technical Specifications – Storage

Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

#### 512GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen4
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 860MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

1TB M.2 2280 PCIe NVMe SSD		
Drive Weight	< 10g	
Capacity	1TB	
Height	2.38mm	
Length	80mm	
Width	22mm	
Interface	PCIE Gen4	
Maximum Sequential Read	Up to 1600MB/s	
Maximum Sequential Write	Up to 860MB/s	
Logical Blocks	1,000,215,216	
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]	
Features	APST; ASPM L1.2; NVME spec 1.2	

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

### 512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen4
Maximum Sequential Read	Up to 2900MB/s



## Technical Specifications – Storage

Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

#### 1TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	1 TB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen4
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

#### HP EXTERNAL USB DVD/RW

Drive	Manual try load
	-
Interface	USB 2.0
Dimensions (H x W x D)	0.55 X 5.41 X 5.94 in (1.40 X 14.40 X 13.75 cm)
Form factor	External
Access Times CD 1/3 STROKE	140 ms
DVD 1/3 Stroke	160 ms
Supported media (read)	DVD-ROM, DVD-R DVD-R, DVD-R DL, DVD-RW, DVD+R, DVD+R DL, AND +RW CD-ROM, CD-ROM XA, CD-DA SUPER AUDIO CD CD-R DISCS CD-RW DISCS CPRM (DVD-R/RW/RAM) SUPPORTED
Supported media (write)	DVD-R DVD-R DL DVD-RW DVD+R DVD+R DL DVD+RW CD-R/RW
System requirements	Pentium IV 2.4GHz or higher, Compatible (recommended: Pentium IV 3.2GHz or higher)



Technical Specifications – Storage

RAM	256MB or higher (recommended: 128MB)
HDD	20GB or more of available space
Video memory	64MB or higher (recommend: 128MB)
Maximum speed normal	
Write Speeds	S DVD-RW 6X MAXIMUM BY ZCLV DVD+RW 8X MAXIMUM BY ZCLV CD-RW 24 X MAXIMUM BY ZCLV
Read Speeds	S DVD-R/RW/ROM 8 X MAXIMUM DVD-R DL 8 X MAXIMUM DVD-VIDEO 4 X MAXIMUM M-DISC (DVD+R SL) 8 X MAXIMUM DVD+R/+RW 8 X MAXIMUM DVD+R DL 8 X MAXIMUM CD-R/RW/ROM 24 X MAXIMUM CD-DA 24 X MAXIMUM
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)
Environmental conditions (All conditions, non- condensing)	Temperature (operating, read and write): 41°F to 104°F (5°C to 40°C) Relative Humidity (operating): 10% to 80% Relative Humidity (non-condensing, read): 15% to 85% Relative Humidity (depending on temperature, write): 15% to 85% Temperature (non-operating): -22°F to 104°F (-30°C to 40°C) Relative Humidity (non-operating, non-condensing): 10% to 90%
Option kit contents	HP Mobile USB DVD/RW Drive, software, documentation

**NOTE:** Actual speeds may vary. Intended only for creation and storage of original material and other lawful uses. Double layer discs may not be compatible with many existing single layer DVD drives and players.



Technical Specifications - Audio

## **HIGH DEFINITION AUDIO**

Туре	Integrated
HD Audio Codec	Realtek ALC3274 Audio Codec
Audio I/O Ports	Rear 3.5mm combo (microphone/headphone) jack (32 Ohm) supporting CTIA and OMTP style headset Microphone (2K Ohm)
Analog Audio	Yes
Internal Speaker Amplifier	2W per channel stereo amplifier for the internal speakers only
Internal Speaker	Yes - Stereo Speaker
DAC Sampling Rates	44.1 kHz/48 kHz/96 kHz/192 kHz
ADC Sampling Rates	44.1 kHz/48 kHz/96 kHz/192 kHz



Technical Specifications – Input/Output

## **INPUT/OUTPUT DEVICES**

HP Wireless Keyboard		
	Keys	104, 105 lay out (depending upon country)
Physical Characteristics	Dimensions (L x W x H)	18.15 x 6.02 x 1.08 in (461 x 153 x 27.4 mm)
	Weight	1.32 lb (600g) min
	Operating voltage	5 VDC, +/-5%
	Power consumption	50mA Max (All LED on)
Electrical	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
	Keycaps	Mid-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
Mechanical	Switch life	10 million keystrokes (Life tester)
riccianical	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
Environmental	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence

## Technical Specifications – Input/Output

HP USB Wireless Mouse		
Dimensions (H x L x W)	4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mmm)	
Weight	0.19lb (90g)	
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
Environmental	Non-operating humidity	20% to 80% (non-condensing at ambient)
Liivii oliinentat	Operating shock	50 g, 6 surfaces
	Non-operating shock	80 g, 6 surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Operating voltage	5 VDC, +/-5%
	Power consumption	50mA Max
Electrical	Resolution	800, 1200, 1600 DPI
	Tracking speed	31 inch/sec (max)
	Tracking acceleration	8G(max), 1G=9.8m/s3
Mechanical	Connector	USB 2.0
ricciidillal	Cable length	6 ft (1.8 m)



Technical Specifications – Input/Output

#### HP Universal USB Wired Keyboard

	Keys	104, 105 layout (depending upon country)
Physical Characteristics	Dimensions (L x W x H)	18.15 x 6.02 x 1.08 in (461 x 153 x 27.4 mm)
	Weight	1.32 lb (600g) min
	Operating voltage	5 VDC, +/-5%
	Power consumption	50mA Max (All LED on)
Electrical	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
	Keycaps	Mid-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
Mechanical	Switch life	10 million keystrokes (Life tester)
Mechanical	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
Environmental	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence

## Technical Specifications – Input/Output

#### **HP USB Universal Wired Mouse**

<b>Dimensions</b> (H x L x W)	4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mmm)		
Weight	0.19lb (90g)		
	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
Environmental	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	50 g, 6 surfaces	
	Non-operating shock	80 g, 6 surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
	Operating voltage	5 VDC, +/-5%	
	Power consumption	50mA Max	
Electrical	Resolution	800, 1200, 1600 DPI	
	Tracking speed	31 inch/sec (max)	
	Tracking acceleration	8G(max), 1G=9.8m/s3	
Mechanical	Connector	USB 2.0	
rictianitat	Cable length	6 ft (1.8 m)	



## Technical Specifications – Input/Output

ΗP	USB	Optical	Mouse

<b>Dimensions</b> (H x L x W)	4.53 x 2.50 x 1.40 in (115 x 63.46 x 35.48 mmm)		
Weight	0.18lb (80g)		
	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
Environmental	Non-operating humidity	20% to 80% (non-condensing at ambient)	
Liivii oliinentat	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
	Operating voltage	5 VDC, +/-5%	
	Power consumption	50mA Max	
Electrical	Resolution	1,000 DPI	
	Sensor	Pixart PAN3606DL	
	Tracking speed	30 inch/sec (max)	
	Tracking acceleration	9G(max), 1G=9.8m/s2	
Mechanical	Connector	USB 2.0	
rictionitut	Cable length	6 ft (1.8 m)	

## **NETWORKING/COMMUNICATIONS**

Realtek® RTL8111HSH-CG Gigabit Ethernet Controller	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)
		IEEE 802.3az EEE (Energy Efficient Ethernet) Jumbo Frame 9K Auto MDI/MDIX Crossover cable detection
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Interface	PCI Express 1.1 x1 to fully support ASPM LOs/L1 and CLKREQ
	NIC Device Driver Name	PCIe GBE Ethernet Family Controller

#### WLAN\*

Realtek® 8852BE Wi-Fi 6 <sup>1</sup> (802.11ax) 2x2 with Bluetooth® Wireless Card M.2		
Wireless LAN Standards	IEEE 802.11a	
	IEEE 802.11b	
	IEEE 802.11g	
	IEEE 802.11n	
	IEEE 802.11ac	
	IEEE 802.11ax	
	IEEE 802.11d	
	IEEE 802.11e	
	IEEE 802.11h	
	IEEE 802.11i	
	IEEE 802.11k	
	IEEE 802.11r	
	IEEE 802.11v	
Interoperability	Wi-Fi <sup>®</sup> certified	
Frequency Band	802.11b/g/n/ax	
	• 2.402 – 2.482 GHz	
	802.11a/n/ac/ax	
	• 4.9 – 4.95 GHz (Japan)	
	• 5.15 – 5.25 GHz	
	• 5.25 – 5.35 GHz	



	• 5.47 – 5.725 GHz • 5.825 – 5.850 GHz	
Data Rates	<ul> <li>• 5.825 - 5.850 GHZ</li> <li>• 802.11b: 1, 2, 5.5, 11 Mbps</li> <li>• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps</li> <li>• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps</li> <li>• 802.11n: max 300Mbps</li> <li>• 802.11ac : max 866.7Mbps</li> <li>• 802.11ax : max 1201Mbps</li> </ul>	
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM	
Security <sup>2</sup>	<ul> <li>IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only</li> <li>AES-CCMP: 128 bit in hardware</li> <li>802.1x authentication</li> <li>WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.</li> <li>WPA2 certification</li> <li>WPA3 certification</li> <li>IEEE 802.11i</li> <li>WAPI</li> </ul>	
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power <sup>3</sup>	<ul> <li>802.11b: +18.5dBm minimum</li> <li>802.11g: +17.5dBm minimum</li> <li>802.11a: +18.5dBm minimum</li> <li>802.11a: +18.5dBm minimum</li> <li>802.11n HT20(2.4GHz): +15.5dBm minimum</li> <li>802.11n HT40(2.4GHz): +14.5dBm minimum</li> <li>802.11n HT20(5GHz): +15.5dBm minimum</li> <li>802.11n HT40(5GHz): +14.5dBm minimum</li> <li>802.11ac VHT80(5GHz): +11.5dBm minimum</li> <li>802.11ax HE40(2.4GHz): +10dBm minimum</li> <li>802.11ax HE80(5GHz): +10dBm minimum</li> </ul>	
Power Consumption	<ul> <li>Transmit mode:2.5 W</li> <li>Receive mode:2 W</li> <li>Idle mode: (PSP) 180 mW (WLAN Associated)</li> <li>Idle mode:50 mW (WLAN unassociated)</li> <li>Connected Standby/Modern Standby: 10mW</li> <li>Radio disabled: 8 mW</li> </ul>	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity <sup>4</sup>	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum •802.11ax, MCS11(HE40): -57dBm maximum •802.11ax, MCS11(HE80): -54dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	



Dimensions	Type 2230: 2.3 x 2	2.0 x 30.0 mm	
Weight	Type 2230: 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)	
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio	0 OFF; LED White – Radio ON	
(802.11ax) is backwards compatible wit 2. Check latest software/driver release f 3. Maximum output power may vary by o 4. Receiver sensitivity is measured at a p (OFDM modulation).	h prior 802.11 specs. or updates on supporte country according to loc acket error rate of 8%		
Bluetooth <sup>®</sup> Specification		/5.2 Wireless Card Compliant	
Frequency Band	2402 to 2480 MHz	· · · · · · · · · · · ·	
Number of Available Channels	Legacy: 0~79 (1 MH BLE: 0~39 (2 MHz/C		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps		
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps		
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels. Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power		ponent shall operate as a Class II Bluetooth device with a maximum - 4 dBm for BR and EDR.	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 1	I7 mW	
Bluetooth® Software Supported Link Topology	Microsoft Windows	Bluetooth® Software	
Power Management	Microsoft Windows	ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 1 ETS 300 328, ETS 3 Low Voltage Directi UL, CSA, and CE Mar	ve IEC950	
Bluetooth Profiles Supported	Train Nudging & Int BT4.2 ESR08 Compl LE Secure Connection LE Privacy 1.2 –Link	Directed Advertising on Oriented Channels erlaced Scan liance on- Basic/Full	



LE Data Packet Length Extension
FAX Profile (FAX)
Basic Imaging Profile (BIP)2
Headset Profile (HSP)
Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP)
BT5.1
ESR9/10 Compliance
LE Advertisement Extensions
Channel Selection Algo
Limited High Duty Cycle Non-Connectable Advertising
2Mbps LE
LE Long Range



Realtek RT 8852BE-VS Wi-F	i 6 <sup>1</sup> (802.11ax) 1x1 with Bluetooth <sup>®</sup> Wireless Card M.2
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g
	IEEE 802.11n IEEE 802.11ac
Interoperability	Wi-Fi <sup>®</sup> certified
Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	<ul> <li>802.11b: 1, 2, 5.5, 11 Mbps</li> <li>802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps</li> <li>802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps</li> <li>802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)</li> <li>802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)</li> </ul>
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security <sup>2</sup>	<ul> <li>IEEE 64 / 128 bit WEP encryption for a/b/g mode only</li> <li>AES-CCMP: 128 bit in hardware</li> <li>802.1x authentication</li> <li>WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.</li> <li>WPA2 certification</li> <li>IEEE 802.11i</li> <li>Cisco Certified Extensions, all versions through CCX4 and CCX Lite</li> <li>WAPI</li> </ul>
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power <sup>3</sup>	<ul> <li>802.11b: +14dBm minimum</li> <li>802.11g: +12dBm minimum</li> <li>802.11a: +12dBm minimum</li> <li>802.11n HT20(2.4GHz): +12dBm minimum</li> <li>802.11n HT40(2.4GHz): +12dBm minimum</li> <li>802.11n HT40(5GHz): +10dBm minimum</li> <li>802.11n HT40(5GHz): +10dBm minimum</li> <li>802.11ac VHT80(5GHz): +10dBm minimum</li> </ul>
Power Consumption	<ul> <li>Transmit mode2.0 W</li> <li>Receive mode 1.6 W</li> <li>Idle mode (PSP) 180 mW (WLAN Associated)</li> <li>Idle mode 50 mW (WLAN unassociated)</li> <li>Connected Standby 10mW</li> <li>Radio disabled 8 mW</li> </ul>
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity <sup>4</sup>	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum



## Technical Specifications - Networking

	67dBm maximum		
	802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum		
	802.11ac, MCS9: -59dBm maximum		
Antenna type	High efficiency ant		
		al band 2.4/5 GHz antenna is provided to the card to support WLAN	
	communications and Bluetooth communications		
Form Factor	PCI-Express M.2 M	iniCard	
Dimensions	Туре 2230: 2.3 х 2	2.0 x 30.0 mm	
Weight	Type 2230: 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)	
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio	o OFF; LED White – Radio ON	
<ol> <li>Check latest software/driver release</li> <li>Maximum output power may vary by</li> <li>Receiver sensitivity is measured at a (OFDM modulation).</li> </ol>	y country according to lo	cal regulations. for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g	
HP Integrated Module with Blue	etooth <sup>®</sup> 4.0/4.1/4.2	Wireless Technology	
Bluetooth <sup>®</sup> Specification	4.0/4.1/4.2 Complia	ant	
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps		
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps		
	Legacy: Asynchron	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.		
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW		
Bluetooth® Software Supported Link Topology	Microsoft Windows	Bluetooth® Software	
Power Management	Microsoft Windows	ACPI, and USB Bus Support	
Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Co	ompliance	



LE Link Layer Ping LE Dual Mode

LE Link Layer
LE Low Duty Cycle Directed Advertising
LE L2CAP Connection Oriented Channels
Train Nudging & Interlaced Scan
BT4.2 ESR08 Compliance
LE Secure Connection- Basic/Full
LE Privacy 1.2 –Link Layer Privacy
LE Privacy 1.2 –Extended Scanner Filter Policies
LE Data Packet Length Extension
FAX Profile (FAX)
Basic Imaging Profile (BIP)2
Headset Profile (HSP)
Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP)

	.11ax 2x2 Wi-Fi™ + Bluetooth® 5.4 Wireless Card	
(802.11ax 2x2, supporting g	igabit data rate)1	
Wireless LAN Standards	IEEE 802.11a	
	IEEE 802.11b	
	IEEE 802.11g	
	IEEE 802.11n	
	IEEE 802.11ac	
	IEEE 802.11ax	
	IEEE 802.11d	
	IEEE 802.11e	
	IEEE 802.11h	
	IEEE 802.11i	
	IEEE 802.11k	
	IEEE 802.11r	
	IEEE 802.11v	
Interoperability	Wi-Fi certified modules	
Frequency Band	802.11b/g/n/ax	
	•2.402 – 2.482 GHz	
	802.11a/n/ac/ax	
	•4.9 – 4.95 GHz (Japan)	
	•5.15 – 5.25 GHz	
	•5.25 – 5.35 GHz	
	•5.47 – 5.725 GHz	
	•5.825 – 5.850 GHz	
Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps	
	•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	•802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	•802.11n: max 300Mbps	
	•802.11ac: max 866.7Mbps	
	• 802.11ax: max 1201Mbps	
Modulation	Direct Sequence Spread Spectrum, OFDM,	
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM	
Security <sup>2</sup>	•IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only	
	•AES-CCMP: 128 bit in hardware	
	•802.1x authentication	
	•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.	
	•WPA2 certification	
	•WPA3 certification	



	•IEEE 802.11i				
Network Architecture Models	•WAPI Ad-hoc (Peer to Peer)				
	Infrastructure (Access Point Required)				
Roaming	IEEE 802.11 compliant roaming between access points				
Output Power <sup>3</sup>	• 802.11b: +18.5dBm minimum				
	• 802.11g: +17.5dBm minimum				
	• 802.11a: +18.5dBm minimum				
	• 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum				
	• 802.11n HT20(5GHz): +15.5dBm minimum				
	• 802.11n HT40(5GHz): +14.5dBm minimum				
	• 802.11ac VHT80(5GHz): +11.5dBm minimum				
	• 802.11ax HE40(2.4GHz): +10dBm minimum				
	• 802.11ax HE80(5GHz): +10dBm minimum				
Power Consumption	•Transmit mode: 2.5 W				
	•Receive mode: 2 W				
	•Idle mode (PSP): 180 mW (WLAN Associated)				
	•Idle mode: 50 mW (WLAN unassociated) •Connected Standby/Modern Standby: 10mW				
	•Radio disabled: 8 mW				
hahahPower Management	ACPI and PCI Express compliant power management				
	802.11 compliant power saving mode				
Receiver Sensitivity <sup>4</sup>	802.11b, 1Mbps: -93.5dBm maximum				
	802.11b, 11Mbps: -84dBm maximum				
	802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum				
	802.11n, MCS07: -67dBm maximum				
	802.11n, MCS15: -64dBm maximum				
	802.11ac, MCS0: -84dBm maximum				
	802.11ac, MCS9: -59dBm maximum				
	•802.11ax, MCS11(HE40): -57dBm maximum				
	•802.11ax, MCS11(HE80): -54dBm maximum				
Antenna type	High efficiency antenna with spatial diversity.				
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN				
	MIMO communications and Bluetooth communications				
Form Factor	PCI-Express M.2 MiniCard				
Dimensions	1. Type 2230: 2.4 x 22.0 x 30.0 mm				
Weight	1. Type 2230: 2.8g				
Operating Voltage	3.3v +/- 9%				
Temperature	Operating: 14° to 158° F (–10° to 70° C)				
	Non-operating: –40° to 176° F (–40° to 80° C)				
Humidity	Operating: 10% to 90% (non-condensing)				
-	Non-operating: 5% to 95% (non-condensing)				
Altitude	Operating: 0 to 10,000 ft (3,048 m)				
	Non-operating: 0 to 50,000 ft (15,240 m)				



LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON				
HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0/5.1/5.2/5.3/5.4 Wireless Card Technology					
Bluetooth <sup>®</sup> Specification	4.0/4.1/4.2/5.0/5.1/5.2/5.3/5.4 wireless card compliant				
Frequency Band	2402 to 2480 MHz				
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)				
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)				
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.				
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW				
Bluetooth® Software Supported Link Topology	Supported Microsoft Windows Bluetooth Software				
Power Management	Microsoft Windows ACPI, and USB Bus Support				
Certifications	FCC (47 CFR) Part 15C/E, Section 15.247, 15.249 ETSI 300 328, ETSI 301 893				
Bluetooth <sup>®</sup> Profiles Supported	Bluetooth 4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan Bluetooth 4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) Bluetooth 5.1 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range				



Technical Specifications - Networking

1. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. 1. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Technical Specifications - Power

#### POWER

	Efficiency	65W EPS, 88% average efficiency at 115V & 89% at 230Vac		
	Operating Voltage Range	90Vac~264Vac		
	Rated Voltage Range	100Vac~240Vac		
	Rated Line Frequency	50Hz~60Hz		
	Operating Line Frequency	47Hz~63Hz		
	Rated Input Current	≦1.6A		
	Rated Input Current with Energy Efficient* Power Supply	≦1.6A		
	DC Output	+19.5V		
	Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-Patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-Patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.		
Dimensions		102 x 55 x 30 mm		
		· · · · · · · · · · · · · · · · · · ·		
	Efficiency	90W EPS, 88% average efficiency at 115V & 89% at 230Vac		
	Efficiency Operating Voltage Range	90W EPS, 88% average efficiency at 115V & 89% at 230Vac 90Vac~264Vac		
	Operating Voltage Range			
	Operating Voltage Range Rated Voltage Range	90Vac~264Vac		
	Operating Voltage Range Rated Voltage Range Rated Line Frequency	90Vac~264Vac 100Vac~240Vac		
	Operating Voltage Range Rated Voltage Range	90Vac~264Vac 100Vac~240Vac 50Hz~60Hz		
	Operating Voltage Range Rated Voltage Range Rated Line Frequency Operating Line Frequency Rated Input Current Rated Input Current with Energy	90Vac~264Vac 100Vac~240Vac 50Hz~60Hz 47Hz~63Hz		
	Operating Voltage Range Rated Voltage Range Rated Line Frequency Operating Line Frequency Rated Input Current	90Vac~264Vac 100Vac~240Vac 50Hz~60Hz 47Hz~63Hz ≦1.6A		
	Operating Voltage Range Rated Voltage Range Rated Line Frequency Operating Line Frequency Rated Input Current Rated Input Current with Energy Efficient* Power Supply	90Vac~264Vac 100Vac~240Vac 50Hz~60Hz 47Hz~63Hz ≦1.6A ≦1.6A		
	Operating Voltage Range Rated Voltage Range Rated Line Frequency Operating Line Frequency Rated Input Current Rated Input Current with Energy Efficient* Power Supply DC Output	90Vac~264Vac 100Vac~240Vac 50Hz~60Hz 47Hz~63Hz ≦1.6A ±1.6A +19.5V Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-Patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-Patient Electrical Appliances and Equipment used in a patient care		



Technical Specifications - Environmental

## **ADDITIONAL FEATURES**

Description

SMART Technology (Self-Monitoring, Analysis and Reporting Technology) Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted

Summary of Changes

## **SUMMARY OF CHANGES**

Date of change:	Version History:		Description of change:
July 27, 2023	V1 to V2	Update	Back call outs page corrected
August 1, 2023	V2 to V3	Update	Environmental table updated
June 7, 2024	V3 to V4	Update	Refresh new version
July 2, 2024	V4 to V5	Update	Environmental data table specs updated
August 22,2024	V5 to V6	Update	Disclaimer 1Added to Memory section
December 19, 2024	V6 to V7	Addition	Processor i5-1334U / WLAN Cass: Realtek 8852BE-VT Wi-Fi 6 added
February 20, 2025	V7 to V8	Addition	Realtek RTL8852BE-VT 802.11ax specs table added to N/C section
May 22, 2025	V8 to V9	Removal	Stand specs in ALL-IN-ONE STAND SPECIFICATIONS section removed

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